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U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office 46886

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): Jeong-jai Choi Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies) Name: Samsung Electronics Co., Ltd. Internal Address: Street Address: 416 Mactan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do Korea City: State: Zip: Additional name(s) & address(es) attached? Yes No

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3. Nature of conveyance: Assignment Merger Security Agreement Change of Name Other Execution Date: May 11, 2004

4. Application number(s) or patent number(s): 101860061 If this document is being filed together with a new application, the execution date of the application is: May 11, 2004 A. Patent Application No.(s) B. Patent No.(s) Additional numbers attached? Yes No

6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 3.41) \$ 40.00 Enclosed Authorized to be charged to deposit account 8. Deposit account number: 18-2220

5. Name and address of party to whom correspondence concerning document should be mailed: Name: John E. Holmes Roylance, Abrams, Berdo & Goodman, LLP Internal Address: Street Address: 1300 19th Street, N.W. Suite 600 City: Washington State: DC Zip: 20036

DO NOT USE THIS SPACE

9. Signature. Peter L. Kendall (Reg. No. 46,246) Name of Person Signing Signature Date June 4, 2004

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

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PATENT REEL: 015436 FRAME: 0843

**ASSIGNMENT**

WHEREAS, I, Jeong-jai CHOI, a citizen of the Republic of Korea, residing at 107-1602, Ssangyong Apartment, 553, Bora-ri, Giheung-eup, Yongin-si, Gyeonggi-do, Korea, Republic of Korea (hereinafter ASSIGNOR), have made a certain invention entitled **ELECTROPHOTOGRAPHIC IMAGE-FORMING APPARATUS USING TWO-COMPONENT DEVELOPER AND PRINT DENSITY CONTROL METHOD THEREOF**, which I am making application for Letters Patent of the United States, said application being executed concurrently herewith; and

WHEREAS, Samsung Electronics Co., Ltd., a corporation duly organized under the laws of the Republic of Korea, located and doing business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (hereinafter ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the aforementioned invention and the aforementioned application and any and all United States Letters Patent to be obtained on said invention and/or application;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for good and valuable consideration paid to me by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, by these presents do hereby sell, assign, set over and transfer unto said ASSIGNEE, its successors, legal representatives or assigns, the entire right, title and interest in and to the aforesaid invention in and for the United States; and in, to and under the aforesaid United States application and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be filed on said invention in the United States; and my right to file said applications and claim priority under the provisions of any international convention or treaty; and any Letters Patent of the United States issued or granted on said invention and/or said applications;

AND I HEREBY authorize and request the U.S. Patent and Trademark Office or other issuing authority to issue any and all patents on said invention and/or said application to said ASSIGNEE as sole assignee;

AND I HEREBY covenant that I have the full right to convey the entire right, title and interest herein assigned and that I have not executed and will not execute any assignment or other instrument in conflict herewith;

AND I HEREBY further covenant and agree to communicate to said ASSIGNEE, or its legal representatives, successors or assigns, any facts relating to said invention, including evidence for interference purposes or other proceedings, whenever requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to do everything possible to aid the said ASSIGNEE, its successors, legal representatives or assigns to obtain and enforce proper patent protection on and for said invention in the United States, and

likewise I make these provisions binding upon my heirs, legal representatives and/or administrators.

IN WITNESS WHEREOF, I have hereunder set my hand and seal this 11th day of May, 2004.

Jeong-jai Choi  
Jeong-jai CHOI

ca Choi  
Witness Eun-ji LEE